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ABSTRACT

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There are provided a method and an apparatus for evaluating a wafer configuration which can accurately evaluate a peripheral portion of a wafer as compared with the conventional SFQR or the like, which comprises: measuring a configuration of a wafer at positions with a prescribed space within a surface of the wafer; providing a first region (W1) within the wafer surface for calculating a reference line or a reference plane from the measured wafer configuration; calculating a reference line (10a) or a reference plane (10b) in the first region (W1); providing a second region (W2) to be evaluated outside the first region; extrapolating the reference line (10a) or reference plane (10b) to the second region (W2); analyzing a difference between the configuration of the second region and the reference line or reference plane within the second region; and calculating the analyzed difference as surface characteristics.